

# PNP Silicon Epitaxial Transistor

## BCP69T1G, NSVBCP69T1G

This PNP Silicon Epitaxial Transistor is designed for use in low voltage, high current applications. The device is housed in the SOT-223 package, which is designed for medium power surface mount applications.

### Features

- High Current:  $I_C = -1.0$  A
- The SOT-223 Package Can Be Soldered Using Wave or Reflow.
- SOT-223 package ensures level mounting, resulting in improved thermal conduction, and allows visual inspection of soldered joints. The formed leads absorb thermal stress during soldering, eliminating the possibility of damage to the die.
- NPN Complement is BCP68
- AEC-Q101 Qualified and PPAP Capable
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	-20	Vdc
Collector-Base Voltage	$V_{CBO}$	-25	Vdc
Emitter-Base Voltage	$V_{EBO}$	-5.0	Vdc
Collector Current	$I_C$	-1.0	Adc
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 1) Derate above $25^\circ\text{C}$	$P_D$	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Temperature Range	$T_J, T_{stg}$	-65 to 150	$^\circ\text{C}$

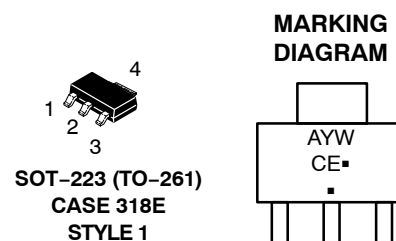
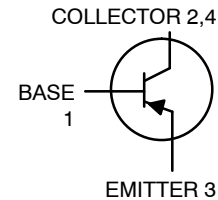
### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance – Junction-to-Ambient (Surface Mounted)	$R_{\theta JA}$	83.3	$^\circ\text{C/W}$
Lead Temperature for Soldering, 0.0625 in from case Time in Solder Bath	$T_L$	260 10	$^\circ\text{C}$ s

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Device mounted on a glass epoxy printed circuit board 1.575 in. x 1.575 in. x 0.059 in.; mounting pad for the collector lead min. 0.93 sq. in.

## MEDIUM POWER PNP SILICON HIGH CURRENT TRANSISTOR SURFACE MOUNT



CE = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
BCP69T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
NSVBCP69T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](http://www.onsemi.com/BRD8011/D).

# BCP69T1G, NSVBCP69T1G

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristics	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = -100 µAdc, I <sub>E</sub> = 0)	V <sub>(BR)CES</sub>	-25	-	-	Vdc
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = -1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-20	-	-	Vdc
Emitter-Base Breakdown Voltage (I <sub>E</sub> = -10 µAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-5.0	-	-	Vdc
Collector-Base Cutoff Current (V <sub>CB</sub> = -25 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	-10	µAdc
Emitter-Base Cutoff Current (V <sub>EB</sub> = -5.0 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	-	-	-10	µAdc
<b>ON CHARACTERISTICS</b>					
DC Current Gain (I <sub>C</sub> = -5.0 mAdc, V <sub>CE</sub> = -10 Vdc) (I <sub>C</sub> = -500 mAdc, V <sub>CE</sub> = -1.0 Vdc) (I <sub>C</sub> = -1.0 Adc, V <sub>CE</sub> = -1.0 Vdc)	h <sub>FE</sub>	50 85 60	- - -	- 375 -	-
Collector-Emitter Saturation Voltage (I <sub>C</sub> = -1.0 Adc, I <sub>B</sub> = -100 mAdc)	V <sub>CE(sat)</sub>	-	-	-0.5	Vdc
Base-Emitter On Voltage (I <sub>C</sub> = -1.0 Adc, V <sub>CE</sub> = -1.0 Vdc)	V <sub>BE(on)</sub>	-	-	-1.0	Vdc
<b>DYNAMIC CHARACTERISTICS</b>					
Current-Gain - Bandwidth Product (I <sub>C</sub> = -10 mAdc, V <sub>CE</sub> = -5.0 Vdc)	f <sub>T</sub>	-	60	-	MHz

## TYPICAL ELECTRICAL CHARACTERISTICS

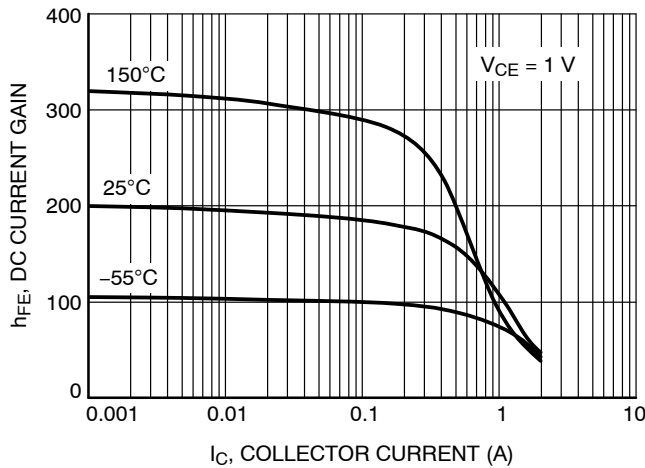


Figure 1. DC Current Gain

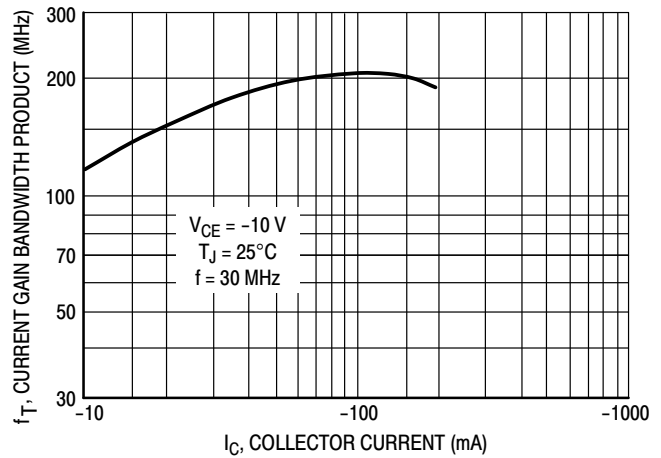
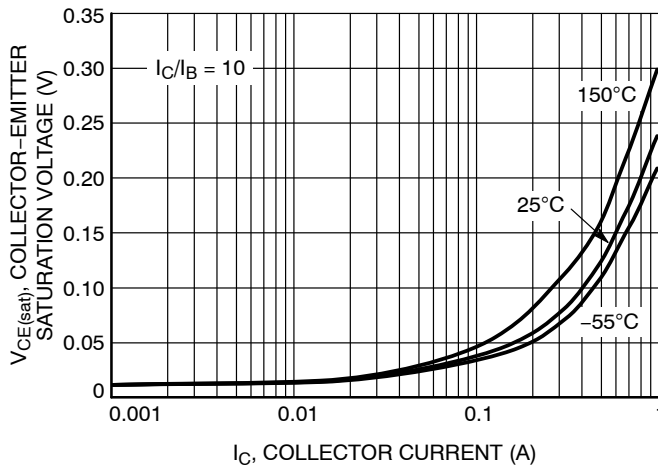


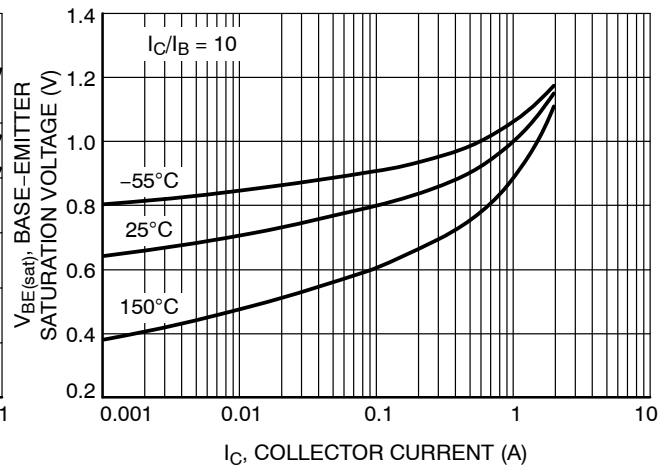
Figure 2. Current Gain Bandwidth Product

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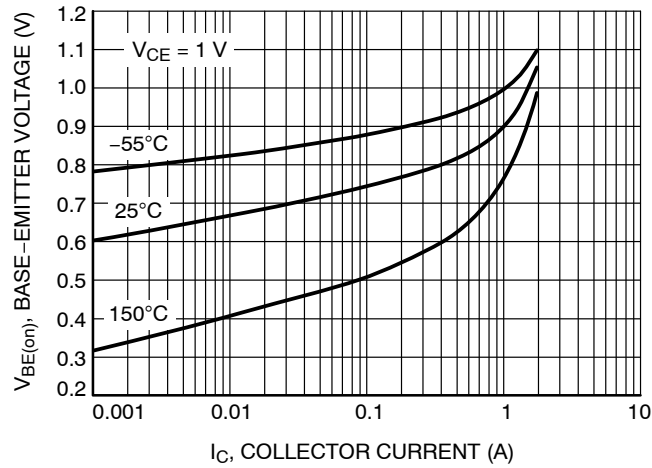
## TYPICAL ELECTRICAL CHARACTERISTICS



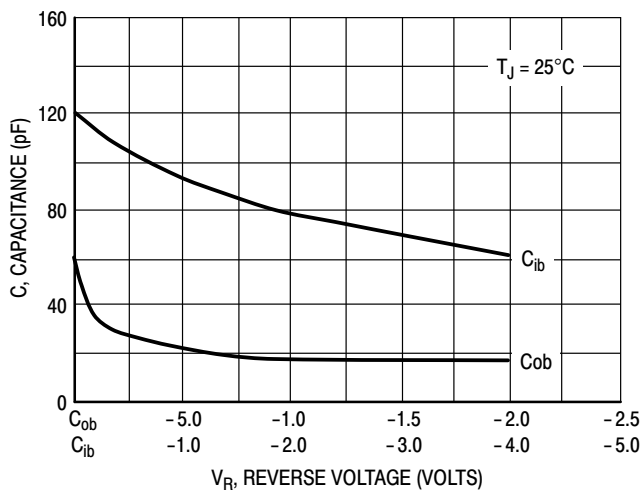
**Figure 3. Collector Emitter Saturation Voltage vs. Collector Current**



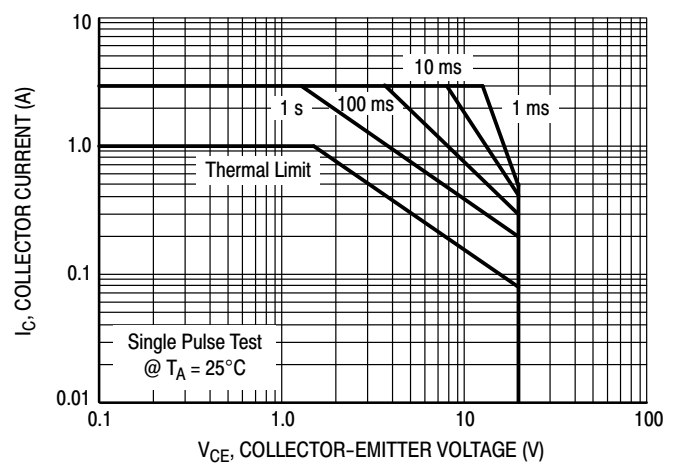
**Figure 4. Base Emitter Saturation Voltage vs. Collector Current**



**Figure 5. Base Emitter Voltage vs. Collector Current**



**Figure 6. Capacitances**



**Figure 7. Safe Operating Area**



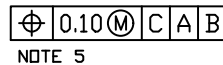
SCALE 1:1

**SOT-223 (TO-261)**  
CASE 318E-04  
ISSUE R

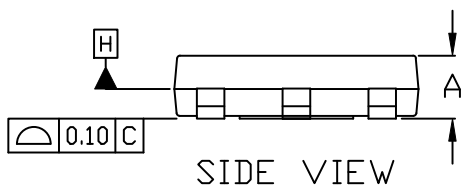
DATE 02 OCT 2018



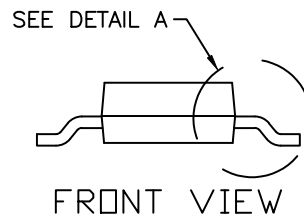
TOP VIEW



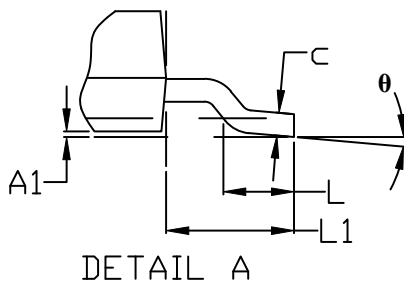
NOTE 5



SIDE VIEW



FRONT VIEW

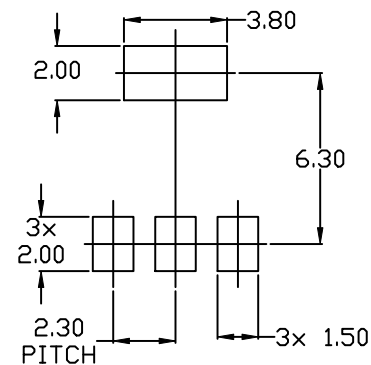


DETAIL A

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
4. DATUMS A AND B ARE DETERMINED AT DATUM H.
5. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS b AND b1.

MILLIMETERS			
DIM	MIN.	NOM.	MAX.
A	1.50	1.63	1.75
A1	0.02	0.06	0.10
b	0.60	0.75	0.89
b1	2.90	3.06	3.20
c	0.24	0.29	0.35
D	6.30	6.50	6.70
E	3.30	3.50	3.70
e	2.30 BSC		
L	0.20	---	---
L1	1.50	1.75	2.00
He	6.70	7.00	7.30
θ	0°	---	10°


RECOMMENDED MOUNTING  
FOOTPRINT

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**SOT-223 (TO-261)**  
**CASE 318E-04**  
**ISSUE R**

DATE 02 OCT 2018

<b>STYLE 1:</b> PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	<b>STYLE 2:</b> PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	<b>STYLE 3:</b> PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	<b>STYLE 4:</b> PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	<b>STYLE 5:</b> PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
<b>STYLE 6:</b> PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	<b>STYLE 7:</b> PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	<b>STYLE 8:</b> CANCELLED	<b>STYLE 9:</b> PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	<b>STYLE 10:</b> PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
<b>STYLE 11:</b> PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	<b>STYLE 12:</b> PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	<b>STYLE 13:</b> PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

**GENERIC  
MARKING DIAGRAM\***



A = Assembly Location  
 Y = Year  
 W = Work Week  
 XXXXX = Specific Device Code  
 ▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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